| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments | ErrorDefinition | Errors |
|---|---|---|---|---|---|---|---|---|---|
| 1 | BRS | L1 | 8 | tft and silsesquioxane | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 18:31 | | | 0 |
| 2 | BRS | L2 | 11 | organic adj fet | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 18:31 | | | 0 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments | ErrorDefinition | Errors |
|---|---|---|---|---|---|---|---|---|---|
| 1 | BRS | L1 | 2112 | silsesquioxane | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/19 08:18 | | | 0 |
| 2 | BRS | L2 | 461 | 1 and cure | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/19 08:18 | | | 0 |
| 3 | BRS | L3 | 244 | 1 and (cure same (temperature or degrees or degree)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/19 08:43 | | | 0 |
| 4 | IS&R | L4 | 3 | ("5384376").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/19 09:28 | | | 0 |
| 5 | IS&R | L5 | 3 | ("5500537").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/19 09:28 | | | 0 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|---|---|---|---|---|---|---|---|---|---|
| 1 | BRS | L1 | 2111 | silsesquioxane | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:20 | | | 0 |
| 2 | BRS | L2 | 1143 | 1 and organic | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:20 | | | 0 |
| 3 | BRS | L3 | 22 | 2 and (FET or (field adj effect adj transistor)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:21 | | | 0 |
| 4 | BRS | L4 | 153 | 2 and (FET or (field adj effect adj transistor) or transistor) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:21 | | | 0 |
| 5 | BRS | L5 | 197 | 1 and (low adj temperature) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:22 | | | 0 |
| 6 | BRS | L6 | 19 | 5 and ((low adj temperature) same cure) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 11:53 | | | 0 |
| 7 | BRS | L7 | 178 | 5 not 6 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 12:38 | | | 0 |
| 8 | IS&R | L8 | 2 | ("6066574").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 12:54 | | | 0 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments | ErrorDefinition | Errors |
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| 9 | BRS | L9 | 112 | 4 not 7 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 12:54 | | | 0 |
| 10 | BRS | L10 | 111 | 9 not 5 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/18 12:54 | | | 0 |

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L1: Entry 1 of 1 File: JPAB Aug 18, 1992

PUB-NO: JP404228415A
DOCUMENT-IDENTIFIER: JP 04228415 A
TITLE: METHOD FOR CONVERTING SILICA PRECURSOR INTO SILICA AT LOW TEMPERATURE BY USING AMINE CATALYST

PUBN-DATE: August 18, 1992

INVENTOR-INFORMATION:
NAME COUNTRY
BANEY, RONALD HOWARD
BILGRIEN, CARL J
BRODERICK, DENNIS W
CARPENTER, LESLIE EARL

ASSIGNEE-INFORMATION:
NAME COUNTRY
DOW CORNING CORP

APPL-NO: JP03130982
APPL-DATE: June 3, 1991

INT-CL (IPC): C01B 33/12; B01J 6/00; C04B 41/50; C09D 183/02; C09D 183/04

ABSTRACT:

PURPOSE: To provide the method for converting hydrogen silsesquioxane resin or hydrolyzed or partially hydrolyzed R

CONSTITUTION: This converting method comprises a process (1) for coating a base with a silica precursor coating, a process (2) for exposing the coating to an atmosphere containing amine, and a process (3) for applying sufficient heat for the formation of the ceramic coating to the coating.

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silsesquioxane <and> cure

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1 **The material characteristics of a new methyl-phenyl silsesquioxane glass for use in a global nonetchback interconnect planarization pr ce**
*Allman, D.D.J.; Fuchs, K.P.; Kwong, D.L.*
VLSI Multilevel Interconnection Conference, 1991, Proceedings., Eighth Intern
IEEE , 1991
Page(s): 373 -375

[Abstract] [PDF Full-Text (300 KB)] **CNF**

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*Igaku, Y.; Matsui, S.; Ishigaki, H.; Fujita, J.; Ishida, M.; Ochiai, Y.; Komuro, M Hiroshima, H.; Namatsu, H.*
Microprocesses and Nanotechnology Conference, 2001 International , 2001
Page(s): 106 -107

[Abstract] [PDF Full-Text (402 KB)] **CNF**

2 **Ultra low-k porous silicon dioxide films from a plasma process**
*Qingyan Han; Wei Chen; Waldfried, C.; Escorcia, O.; Sbrockey, N.M.; Bridgew Moyer, E.S.; Berry, I.*
Interconnect Technology Conference, 2001. Proceedings of the IEEE 2001 Inte , 2001
Page(s): 171 -173

[Abstract] [PDF Full-Text (240 KB)] **CNF**

3 **A new four-level metal interconnect system tailored to an advanced mu/m BiCMOS technology**
*Wall, R.N.; Olewine, M.C.; Augur, R.; DiGregorio, J.; Colovos, G.*
Semiconductor Manufacturing, IEEE Transactions on , Volume: 11 Issue: 4 , N
Page(s): 624 -635

[Abstract] [PDF Full-Text (380 KB)] **JNL**

4 **An integrated low resistance aluminum plug and l w-k polymer diel high perf rmance 0.25 /spl mu/m interc nnects**
*Dixit, G.A.; Taylor, K.J.; Singh, A.; Lee, C.K.; Shinn, G.B.; Konecni, A.; Hsu, W Brennan, K.; Mi-Chang Chang; Havemann, R.H.*

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